Abstracts

Passive integration on Si for RF circuits in wireless applications

N.J. Pulsford, J.T.M. Van Beek, M.H.W.M. Van Delden, A. Boogaard and R.F. Milsom. "Passive integration on Si for RF circuits in wireless applications." 1999 MTT-S International Microwave Symposium Digest 99.4 (1999 Vol. IV [MWSYM]): 1897-1900 vol.4.

A technology is described for the integration of high quality factor inductors and capacitors on high ohmic silicon. The performance is optimised for resonator and matching circuits in RF wireless applications. This is demonstrated by the design and measurement of an integrated output match for a GSM power amplifier which has comparable performance to a conventional hybrid module.

❏ Return to main document.

Click on title for a complete paper.